

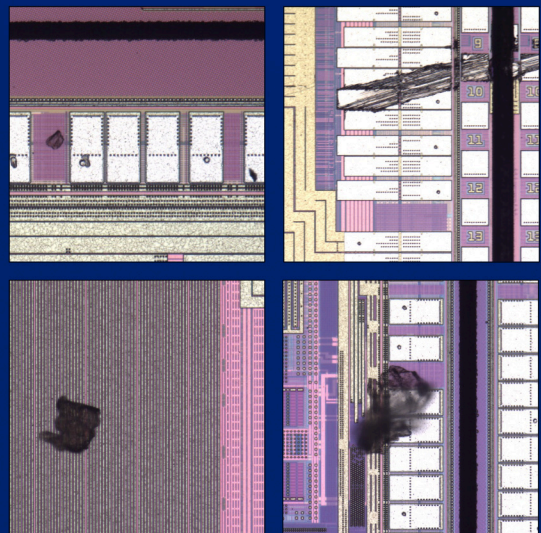
F2X PRO

Wafer AOI designed for Wafer and Sawn Wafer Configuration



Featuring

- Comprehensive Surface, Probe, Sawing, Bump Defect Inspection
- Designed for Wafer and Sawn Wafer
- Minimum or Zero Conversion
- Dual Gate Detection Algorithms (Rule-based and AI-based)
- Vibration Isolated Granite Stage
- Multi Magnification Inspection
- Multi Illumination Channels
- AI-assisted Defect Classification
- Intuitive Review Software
- Scalable Performance Upgrade



F2X PRO SPECIFICATION

HANDLING	
Wafer Size	8" & 12"
Mounted Wafer	8" & 12"
Loadport	• Single, Dual or Customized • 300mm FOUP or FOSB • 200mm and 300mm Open Cassette • 200mm and 300mm Mounted Wafer Magazine
Wafer Transfer	Dual Arm Cleanroom Robot
Mounted Wafer Transfer	Gripper
OS	MS Windows11 and above
Communication	SECSGEM
Cleanroom	ISO 4

2D Surface Inspection			
Magnification	2X	5X	10X
Accuracy (μm)	5	2	1
Throughput (WPH)	60	35	15
Min Defect Size	2 x 2 Pixels		
Illumination	Multi Channel		

Saw Defects
Saw Offset
Kerf Width
Incomplete Saw
Chipping

Surface Defects
Crack
Scratch
Foreign Material
Discoloration
Probe Mark

Bump Defects
Bump Offset
Bump Deform
Bump Size
Bump Contrast

FACILITIES	
Size (mm)	1750(W) x 2700(D) x 2250(H)
Weight	2000KG
Power	230VAC, 50Hz, 20A, 1Ph
CDA	5 – 6 Bars, 1 CFM

HEADQUARTER

Add : Plot 106, Hilir Sungai Keluang 5, Bayan Lepas Industrial Zone Phase 4, Penang, Malaysia, 11900.

Tel : +604-645 6294

Fax : +604-645 6295

Email : sales@ttvision-tech.com

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SCAN FOR MORE INFO

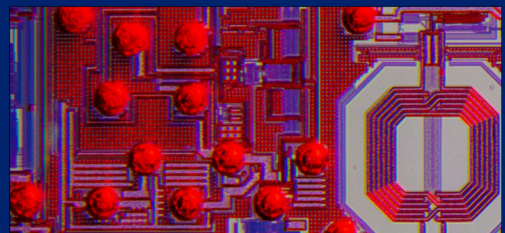
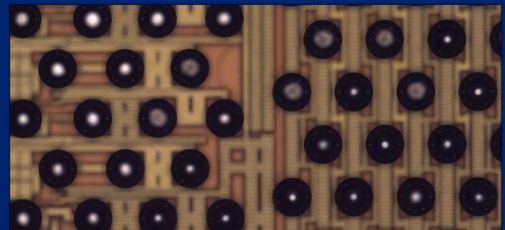
F2X PRO+

Wafer AOI designed for 2D Surface Inspection & 3D Metrology



Featuring

- Comprehensive Surface, Probe, Sawing, Bump Defect Inspection
- 3D Bump Height Metrology from 5 - 250um
- Minimum or Zero Conversion
- Dual Gate Detection Algorithms (Rule-based and AI-based)
- Vibration Isolated Granite Stage
- Multi Magnification Inspection
- Multi Illumination Channels
- AI-assisted Defect Classification
- Intuitive Review Software
- Scalable Performance Upgrade



F2X PRO + SPECIFICATION

HANDLING	
Wafer Size	8" & 12"
Mounted Wafer	8" & 12"
Loadport	• Single, Dual or Customized • 300mm FOUP or FOSB • 200mm and 300mm Open Cassette • 200mm and 300mm Mounted Wafer Magazine
Wafer Transfer	Dual Arm Cleanroom Robot
Mounted Wafer Transfer	Gripper
OS	MS Windows11 and above
Communication	SECSGEM
Cleanroom	ISO 4

2D Surface Inspection			
Magnification	2X	5X	10X
Accuracy (μm)	5	2	1
Throughput (WPH)	60	35	15
Min Defect Size	2 x 2 Pixels		
Illumination	Multi Channel		

3D Bump Metrology			
Accuracy (μm)	10	5	1
Throughput (WPH)	30	17	7
Min Bump Height	5μm		

Surface Defects
Crack
Scratch
Foreign Material
Discoloration
Probe Mark

Saw Defects
Saw Offset
Kerf Width
Incomplete Saw
Chipping

Bump Defects
Bump Offset
Bump Deform
Bump Size
Bump Contrast

3D Bump Metrology
Bump Height
Bump Coplanarity

FACILITIES	
Size (mm)	1750(W) x 3000(D) x 2250(H)
Weight	2300KG
Power	230VAC, 50Hz, 20A, 1Ph
CDA	5 – 6 Bars, 1 CFM

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F2X S3i

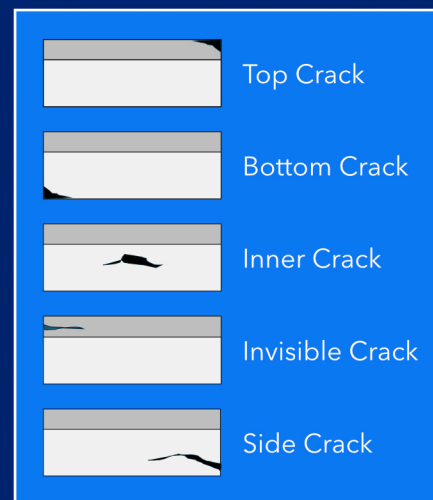
Wafer AOI dedicated for Invisible μ Crack on Sawn Wafer

Patent Pending



Featuring

- Superior Sub-surface Scanning & Inspection
- Unprecedented Wafer Thickness Penetration
- Heavy Doped Wafer Transmission
- Minimum or Zero Conversion
- Dual Gate Detection Algorithms
- (Rule-based and AI-based)
- Vibration Isolated Granite Stage
- Multi Magnification Inspection
- Multi Illumination Channels
- AI-assisted Defect Classification
- Intuitive Review Software
- Scalable Performance Upgrade



F2X S3i SPECIFICATION

HANDLING	
Mounted Wafer	8" & 12"
Loadport	• Single, Dual or Customized • 200mm and 300mm Mounted Wafer Magazine
Wafer Transfer	Dual Arm Cleanroom Robot
Mounted Wafer Transfer	Gripper
OS	MS Windows11 and above
Communication	SECSGEM
Cleanroom	ISO 4

2D Surface Inspection			
Magnification	5X	10X	20X
Accuracy (µm)	1.4	0.7	0.35
Throughput (WPH)	20	10	5
Min Defect Size	2 x 2 Pixels		
Illumination	Multi Channel		

µCrack Inspection			
Magnification	5X	10X	20X
Throughput (WPH)	1	0.5	0.25

Surface Defects	
Crack	
Scratch	
Foreign Material	
Discoloration	
Probe Mark	

µCrack Defects	
Invisible Crack	
Bottom Crack	
Side Crack	
Inner Crack	

FACILITIES	
Size (mm)	1750(W) x 3100(D) x 2250(H)
Weight	2200KG
Power	230VAC, 50Hz, 20A, 1Ph
CDA	5 – 6 Bars, 1 CFM

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